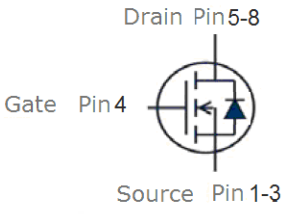
Features

- N-Channel，5V Logic Level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ V_{GS}=4.5 V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant

V_{DS}	60	V
$R_{DS(on),TYP}$@ V_{GS}=10 V	5.5	mΩ
$R_{DS(on),TYP}$@ V_{GS}=4.5V	6.5	mΩ
I_D	20	A

Pb-Free RoHS HF Halogen-Free

SOP8



Part ID	Package Type	Marking	Tape and reel information
VS6019AS	SOP8	6019AS	3000pcs/Reel

Maximum ratings, at T_j=25 °C, unless otherwise specified

Symbol	Parameter		Rating	Unit
Common Ratings (T_C=25°C Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage		±20	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage		60	V
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	°C
I_S	Diode Continuous Forward Current	T_A=25°C	20	A
Mounted on Large Heat Sink				
I_D	Continuous Drain current@VGS=10V	T_A=25°C	20	A
		T_A=100°C	12.5	A
I_{DM}	Pulse Drain Current Tested ①	T_A=25°C	80	A
P_D	Maximum Power Dissipation	T_A=25°C	3.1	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case		24	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient		40	°C/W
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed ②		196	mJ

Electrical Characteristics(at T_j=25 °C, unless otherwise specified)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_C = 25°C (unless otherwise stated)						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V I_D=250μA	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current(T_A=25℃)	V_{DS}=60V,V_{GS}=0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T_A=125℃)	V_{DS}=60V,V_{GS}=0V	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS}=±20V,V_{DS}=0V	--	--	±100	nA
$V_{GS(TH)}$	Gate Threshold Voltage	V_{DS}=V_{GS},I_D=250μA	1	2	3	V
$R_{DS(ON)}$	Drain-Source On-State Resistance③	V_{GS}=10V, I_D=8A	--	5.5	7.0	mΩ
$R_{DS(ON)}$	Drain-Source On-State Resistance③	V_{GS}=4.5V, I_D=4A	--	6.5	10.0	mΩ
Dynamic Electrical Characteristics @ T_C= 25°C (unless otherwise stated)						
R_g	Gate Resistance	V_{DS}=30V,V_{GS}=0V, f=1MHz	--	1.8	--	Ω
C_{iss}	Input Capacitance		--	2800	--	pF
C_{oss}	Output Capacitance		--	290	--	pF
C_{rss}	Reverse Transfer Capacitance		--	250	--	pF
Q_g	Total Gate Charge	V_{DS}=30V,I_D=10A, V_{GS}=10V	--	58	--	nC
Q_{gs}	Gate-Source Charge		--	11	--	nC
Q_{gd}	Gate-Drain Charge		--	19	--	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{DD}=30V, I_D=1A, R_G=6.8Ω, V_{GS}=10V	--	16	--	nS
t_r	Turn-on Rise Time		--	25	--	nS
$t_{d(off)}$	Turn-Off Delay Time		--	58	--	nS
t_f	Turn-Off Fall Time		--	12	--	nS
Source- Drain Diode Characteristics@ T_C = 25°C (unless otherwise stated)						
V_{SD}	Forward on voltage	I_{SD}=8A,V_{GS}=0V	--	0.74	1.2	V
t_{rr}	Reverse Recovery Time	T_j=25℃,I_{sd}=10A, V_{GS}=0V di/dt=100A/μs	--	38	--	nS
Q_{rr}	Reverse Recovery Charge			84		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH,R_G = 25Ω, I_{AS} = 28A, V_{GS} =10V. Part not recommended for use above this value

③ Pulse width ≤ 300μs; duty cycle≤ 2%.

Typical Characteristics

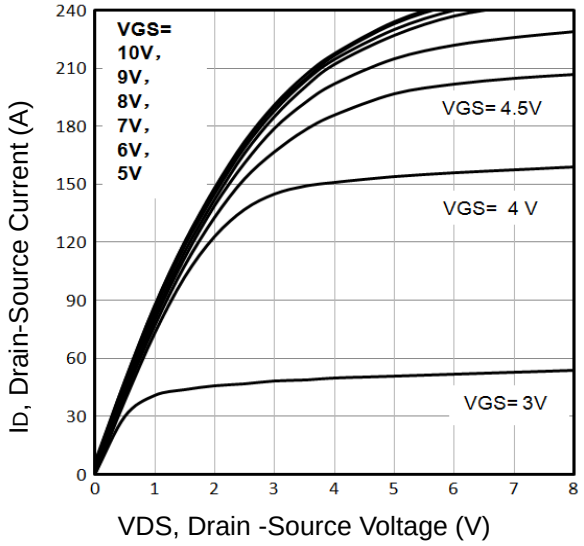


Fig1. Typical Output Characteristics

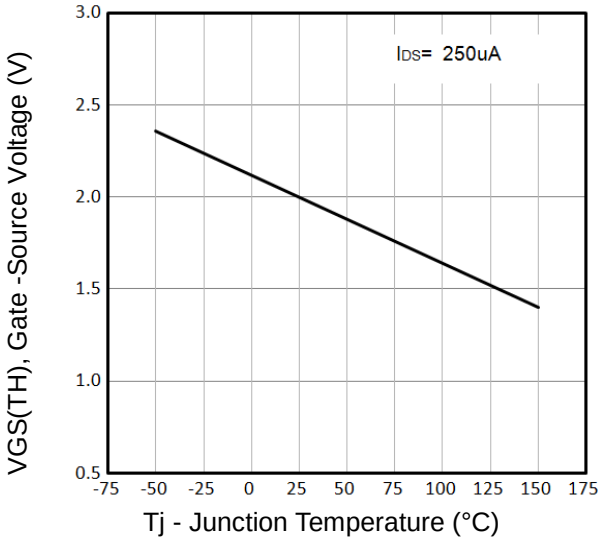


Fig2. Gate -Source Voltage Vs. Temperature

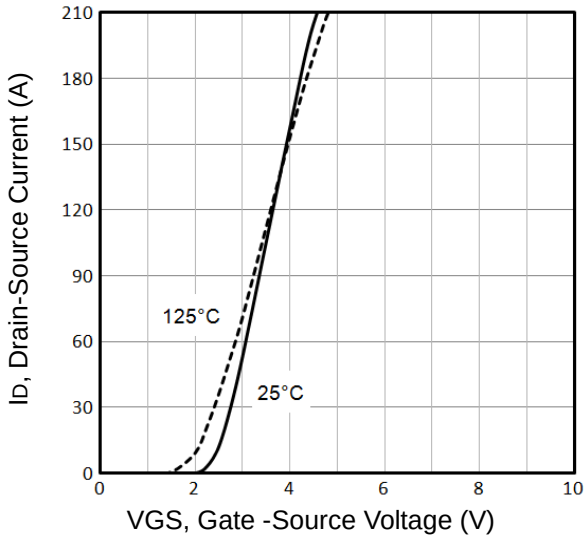


Fig3. Typical Transfer Characteristics

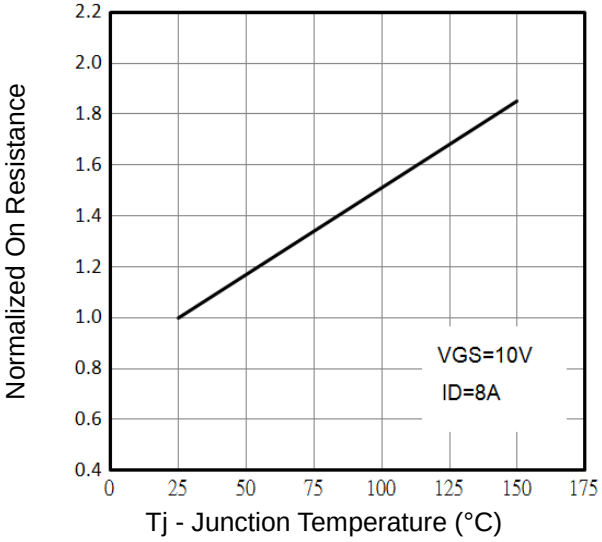


Fig4. Normalized On-Resistance Vs. Temperature

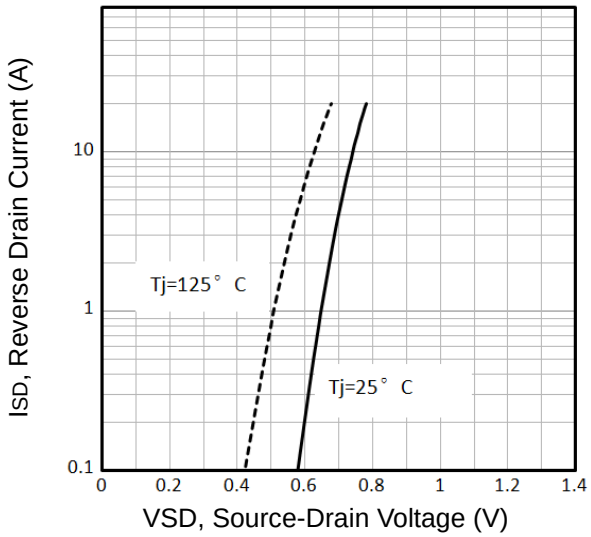


Fig5. Typical Source-Drain Diode Forward Voltage

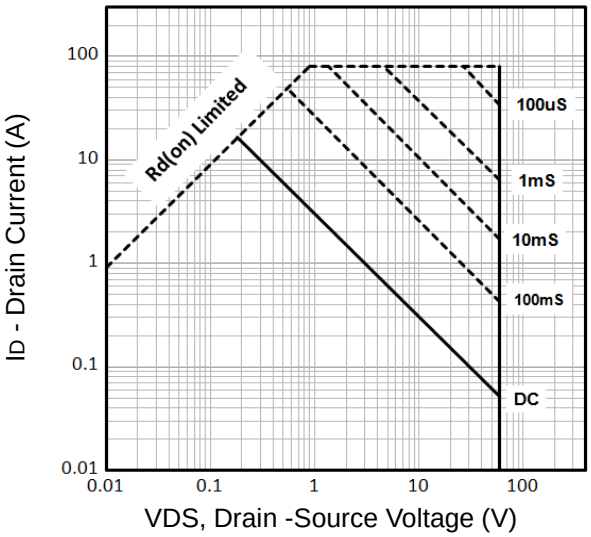


Fig6. Maximum Safe Operating Area

Typical Characteristics

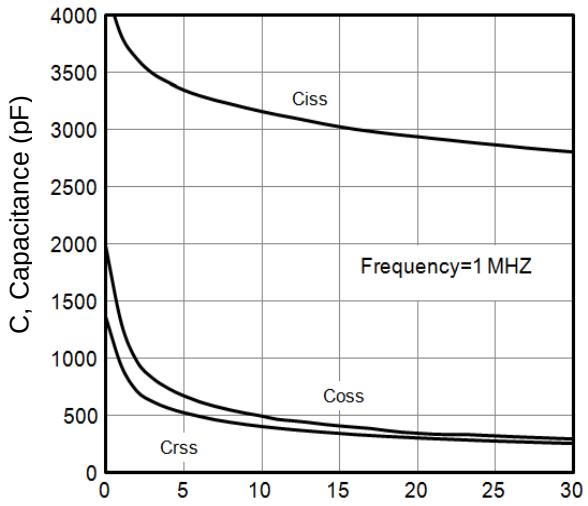


Fig7. Typical Capacitance Vs.Drain-Source

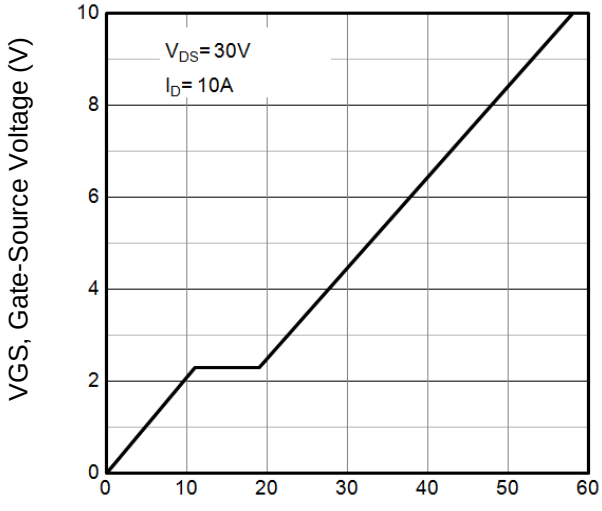


Fig8. Typical Gate Charge Vs.Gate-Source

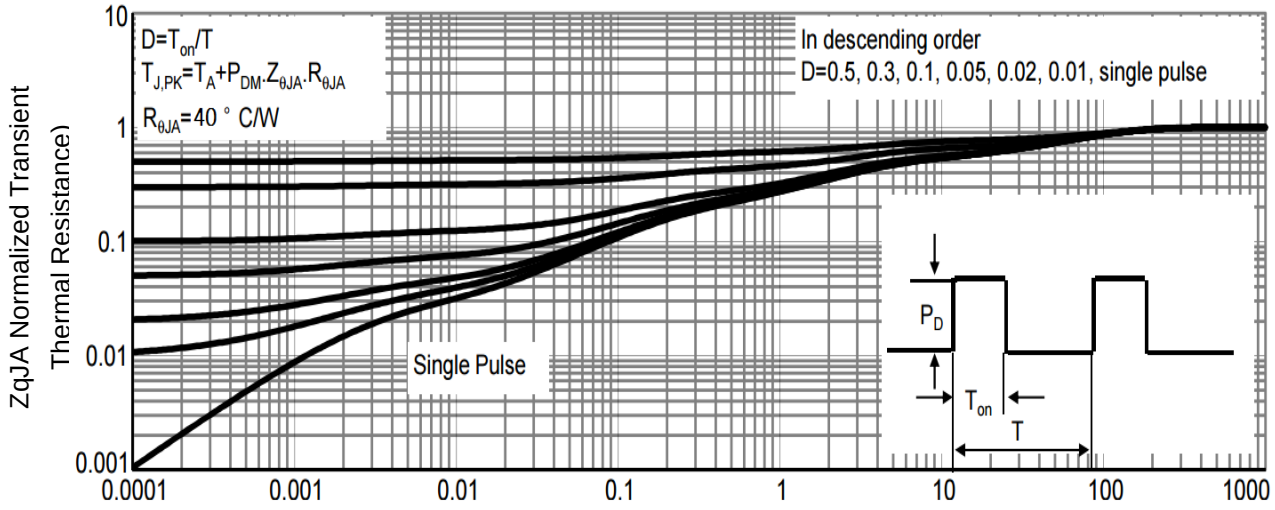


Fig9. Normalized Maximum Transient Thermal Impedance

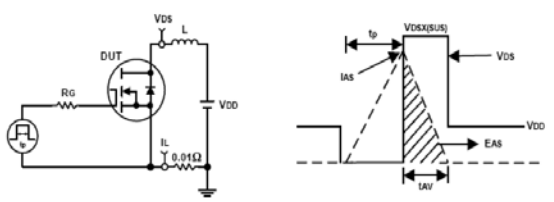


Fig10. Unclamped Inductive Test Circuit and waveforms

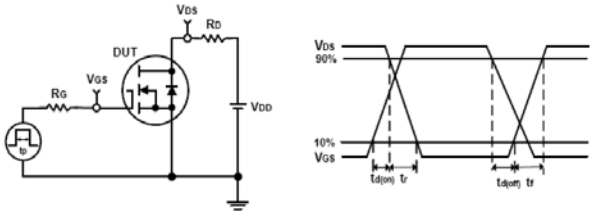
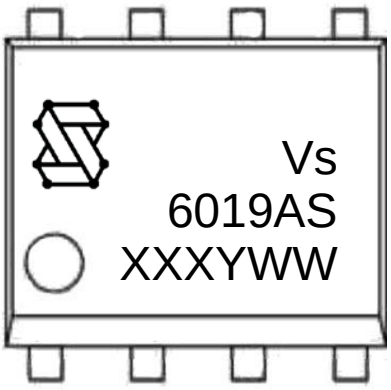


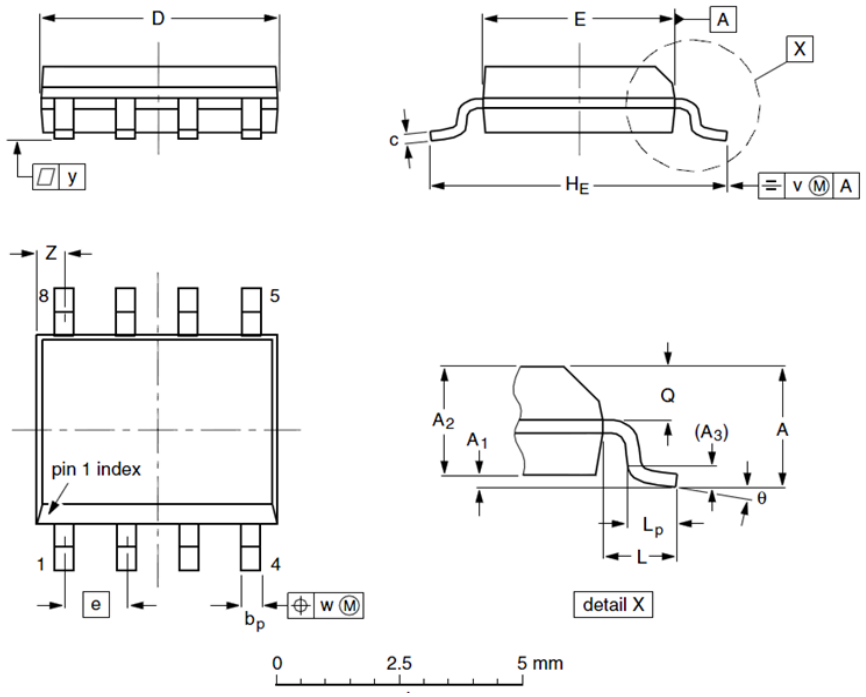
Fig11. Switching Time Test Circuit and waveforms

Marking Information



1st line：Company Code（Vs），Company Logo
2nd line：Part Number（6019AS）
3rd line：Date code （XXXYWW）
XXX：Wafer Lot Number
Y：Year Code，e.g. E means 2017
WW：Week Code

SOP8 Package Outline Data



Label	Dimensions (unit: mm)		
	Min	Typ	Max
A	--	--	1.75
A_1	0.10	0.18	0.25
A_2	1.25	1.35	1.50
A_3	--	0.25	--
b_p	0.36	0.42	0.51
c	0.19	0.22	0.25
D	4.80	4.92	5.00
E	3.80	3.90	4.00
e	--	1.27	--
H_E	5.80	6.00	6.20
L	--	1.05	--
L_p	0.40	0.68	1.00
Q	0.60	0.65	0.725
v	--	0.25	--
w	--	0.25	--
y	--	0.10	--
Z	0.30	0.50	0.70
θ	0°		8°

Notes:

1. Follow JEDEC MS-012.
2. Dimension "D" does NOT include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15mm per side.
3. Dimension "E" does NOT include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25mm per side.
4. Dimension "bp" does NOT include dambar protrusion. Allowable dambar protrusion shall be 0.1mm total in excess of "bp" dimension at maximum material condition. The dambar cannot be located on the lower radius of the foot.

Customer Service

Sales and Service:

sales@vgsemi.com

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: www.vgsemi.com